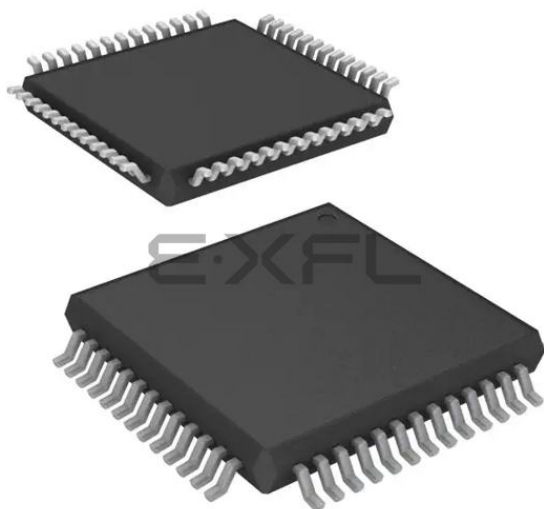




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	47
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	52-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21354cnfp-30

Table 1.5 Pin Name Information by Pin Number (2)

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter, Comparator B
36		P1_2	$\overline{KI2}$	(TRCIOB)				AN10
37		P1_1	$\overline{KI1}$	(TRCIOA/ TRCTRG)				AN9
38		P1_0	$\overline{KI0}$	(TRCIOD)				AN8
39		P0_7		(TRCIOA)				AN0/DA1
40		P0_6		(TRCIOD)				AN1/DA0
41		P0_5		(TRCIOB)				AN2
42		P0_4		TREO (/TRCIOB)				AN3
43		P0_3		(TRCIOB)	(CLK1)			AN4
44		P0_2		(TRCIOA/ TRCTRG)	(RXD1)			AN5
45		P0_1		(TRCIOA/ TRCTRG)	(TXD1)			AN6
46		P0_0		(TRCIOA/ TRCTRG)				AN7
47		P6_4			(RXD1)			
48		P6_3			(TXD1)			
49		P6_2			(CLK1)			
50		P6_1						
51		P6_0		(TREO)				
52		P5_7						

Note:

1. Can be assigned to the pin in parentheses by a program.

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.12 list the special function registers and Table 4.13 lists the ID Code Areas and Option Function Select Area.

Table 4.1 SFR Information (1) ⁽¹⁾

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	0XXXXXXb ⁽²⁾
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h			
0011h			
0012h			
0013h			
0014h			
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0016h			
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b ⁽³⁾
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When Shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When Shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch			
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h			
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h ⁽⁴⁾ 00100000b ⁽⁵⁾
0035h			
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h			
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b ⁽⁴⁾ 1100X011b ⁽⁵⁾
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. The CWR bit in the RSTFR register is set to 0 after power-on and voltage monitor 0 reset. Hardware reset, software reset, or watchdog timer reset does not affect this bit.
3. The CSPROINI bit in the OFS register is set to 0.
4. The LVDAS bit in the OFS register is set to 1.
5. The LVDAS bit in the OFS register is set to 0.

Table 4.3 SFR Information (3) (1)

Address	Register	Symbol	After Reset
0080h	DTC Activation Control Register	DTCTL	00h
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h	DTC Activation Enable Register 0	DTCEN0	00h
0089h	DTC Activation Enable Register 1	DTCEN1	00h
008Ah	DTC Activation Enable Register 2	DTCEN2	00h
008Bh	DTC Activation Enable Register 3	DTCEN3	00h
008Ch	DTC Activation Enable Register 4	DTCEN4	00h
008Dh	DTC Activation Enable Register 5	DTCEN5	00h
008Eh	DTC Activation Enable Register 6	DTCEN6	00h
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART2 Transmit/Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh
00ABh			XXh
00ACh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh
00AFh			XXh
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.4 SFR Information (4) ⁽¹⁾

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.8 SFR Information (8) (1)

Address	Register	Symbol	After Reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h	Address Match Interrupt Enable Register 1	AIER1	00h
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Pull-Up Control Register 0	PUR0	00h
01E1h	Pull-Up Control Register 1	PUR1	00h
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h	Port P1 Drive Capacity Control Register	P1DRR	00h
01F1h	Port P2 Drive Capacity Control Register	P2DRR	00h
01F2h	Drive Capacity Control Register 0	DRR0	00h
01F3h	Drive Capacity Control Register 1	DRR1	00h
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h			
01F8h	Comparator B Control Register 0	INTCMP	00h
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN1	00h
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh	INT Input Filter Select Register 1	INTF1	00h
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.10 SFR Information (10) ⁽¹⁾

Address	Register	Symbol	After Reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2C8Eh			XXh
2C8Fh			XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
2C9Fh			XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACH			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.11 SFR Information (11) ⁽¹⁾

Address	Register	Symbol	After Reset
2CB0h	DTC Control Data 14	DTCD14	XXh
2CB1h			XXh
2CB2h			XXh
2CB3h			XXh
2CB4h			XXh
2CB5h			XXh
2CB6h			XXh
2CB7h			XXh
2CB8h	DTC Control Data 15	DTCD15	XXh
2CB9h			XXh
2CBAh			XXh
2CBBh			XXh
2CBCh			XXh
2CBDh			XXh
2CBEh			XXh
2CBFh			XXh
2CC0h	DTC Control Data 16	DTCD16	XXh
2CC1h			XXh
2CC2h			XXh
2CC3h			XXh
2CC4h			XXh
2CC5h			XXh
2CC6h			XXh
2CC7h			XXh
2CC8h	DTC Control Data 17	DTCD17	XXh
2CC9h			XXh
2CCAh			XXh
2CCBh			XXh
2CCCh			XXh
2CCDh			XXh
2CCEh			XXh
2CCFh			XXh
2CD0h	DTC Control Data 18	DTCD18	XXh
2CD1h			XXh
2CD2h			XXh
2CD3h			XXh
2CD4h			XXh
2CD5h			XXh
2CD6h			XXh
2CD7h			XXh
2CD8h	DTC Control Data 19	DTCD19	XXh
2CD9h			XXh
2CDAh			XXh
2CDBh			XXh
2CDCh			XXh
2CDDh			XXh
2CDEh			XXh
2CDFh			XXh
2CE0h	DTC Control Data 20	DTCD20	XXh
2CE1h			XXh
2CE2h			XXh
2CE3h			XXh
2CE4h			XXh
2CE5h			XXh
2CE6h			XXh
2CE7h			XXh
2CE8h	DTC Control Data 21	DTCD21	XXh
2CE9h			XXh
2CEAh			XXh
2CEBh			XXh
2CECh			XXh
2CEDh			XXh
2CEEh			XXh
2CEFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
—	Resolution		Vref = AVCC		—	—	10	Bit
—	Absolute accuracy	10-bit mode	Vref = AVCC = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±3	LSB
			Vref = AVCC = 3.3 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±5	LSB
			Vref = AVCC = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±5	LSB
			Vref = AVCC = 2.2 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±5	LSB
		8-bit mode	Vref = AVCC = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
			Vref = AVCC = 3.3 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
			Vref = AVCC = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
			Vref = AVCC = 2.2 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
φAD	A/D conversion clock		4.0 V ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	20	MHz
			3.2 V ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	16	MHz
			2.7 V ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	10	MHz
			2.2 V ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	5	MHz
—	Tolerance level impedance				—	3	—	kΩ
tCONV	Conversion time	10-bit mode	Vref = AVCC = 5.0 V, φAD = 20 MHz		2.2	—	—	μs
		8-bit mode	Vref = AVCC = 5.0 V, φAD = 20 MHz		2.2	—	—	μs
tsAMP	Sampling time		φAD = 20 MHz		0.8	—	—	μs
Ivref	Vref current		Vcc = 5 V, XIN = f1 = φAD = 20 MHz		—	45	—	μA
Vref	Reference voltage				2.2	—	AVCC	V
VIA	Analog input voltage (3)				0	—	Vref	V
OCVREF	On-chip reference voltage		2 MHz ≤ φAD ≤ 4 MHz		1.19	1.34	1.49	V

Notes:

- $V_{CC}/AV_{CC} = V_{ref} = 2.2$ to 5.5 V , $V_{SS} = 0\text{ V}$ and $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
- The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
- When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.4 D/A Converter Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	Resolution		—	—	8	Bit
—	Absolute accuracy		—	—	2.5	LSB
t_{su}	Setup time		—	—	3	μs
R_o	Output resistor		—	6	—	$k\Omega$
I_{vref}	Reference power input current	(Note 2)	—	—	1.5	mA

Notes:

1. $V_{CC}/AV_{CC} = V_{ref} = 2.7$ to 5.5 V and $T_{opr} = -20$ to $85^{\circ}C$ (N version) / -40 to $85^{\circ}C$ (D version), unless otherwise specified.
2. This applies when one D/A converter is used and the value of the DA_i register ($i = 0$ or 1) for the unused D/A converter is $00h$. The resistor ladder of the A/D converter is not included.

Table 5.5 Comparator B Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{ref}	$IVREF1$, $IVREF3$ input reference voltage		0	—	$V_{CC} - 1.4$	V
V_i	$IVCMP1$, $IVCMP3$ input voltage		-0.3	—	$V_{CC} + 0.3$	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time ⁽²⁾	$V_i = V_{ref} \pm 100$ mV	—	0.1	—	μs
I_{CMP}	Comparator operating current	$V_{CC} = 5.0$ V	—	17.5	—	μA

Notes:

1. $V_{CC} = 2.7$ to 5.5 V, $T_{opr} = -20$ to $85^{\circ}C$ (N version) / -40 to $85^{\circ}C$ (D version), unless otherwise specified.
2. When the digital filter is disabled.

Table 5.7 Flash Memory (Data flash Block A to Block D) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance ⁽²⁾		10,000 ⁽³⁾	—	—	times
—	Byte program time (program/erase endurance ≤ 1,000 times)		—	160	1,500	μs
—	Byte program time (program/erase endurance > 1,000 times)		—	300	1,500	μs
—	Block erase time (program/erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (program/erase endurance > 1,000 times)		—	0.3	1	s
t _d (SR-SUS)	Time delay from suspend request until suspend		—	—	5+CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	μs
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	μs
t _d (CMDRST-READY)	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		−20 ⁽⁷⁾	—	85	°C
—	Data hold time ⁽⁸⁾	Ambient temperature = 55 °C	20	—	—	year

Notes:

1. V_{CC} = 2.7 to 5.5 V and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. −40°C for D version.
8. The data hold time includes time that the power supply is off or the clock is not supplied.

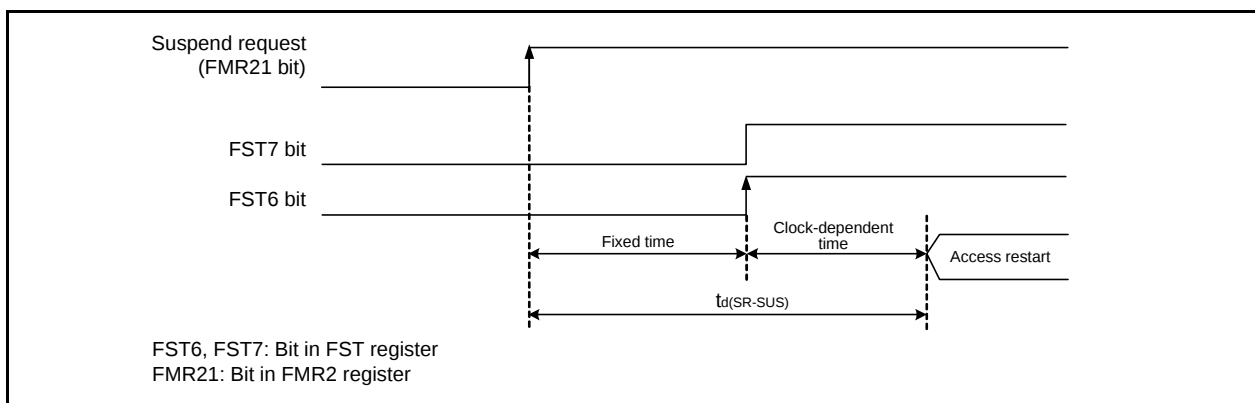
**Figure 5.2 Time delay until Suspend**

Table 5.12 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency after reset	$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	38.4	40	41.6	MHz
		$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	38.0	40	42.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register ⁽²⁾	$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	35.389	36.864	38.338	MHz
		$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	35.020	36.864	38.707	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register	$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	30.72	32	33.28	MHz
		$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	30.40	32	33.60	MHz
–	Oscillation stability time	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	0.5	3	ms
–	Self power consumption at oscillation	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	400	–	μA

Notes:

1. $V_{CC} = 1.8$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.13 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
–	Oscillation stability time	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	30	100	μs
–	Self power consumption at oscillation	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	2	–	μA

Note:

1. $V_{CC} = 1.8$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.

Table 5.14 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _d (P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		–	–	2,000	μs

Notes:

1. The measurement condition is $V_{CC} = 1.8$ to 5.5 V and $T_{opr} = 25^{\circ}\text{C}$.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

Table 5.15 Timing Requirements of Synchronous Serial Communication Unit (SSU) (1)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc (2)
tHI	SSCK clock "H" width			0.4	–	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	–	0.6	tsucyc
tRISE	SSCK clock rising time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tFALL	SSCK clock falling time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
tH	SSO, SSI data input hold time			1	–	–	tcyc (2)
tLEAD	SCS setup time	Slave		1tcyc + 50	–	–	ns
tLAG	SCS hold time	Slave		1tcyc + 50	–	–	ns
tOD	SSO, SSI data output delay time			–	–	1	tcyc (2)
tsa	SSI slave access time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	–	–	$1.5tcyc + 100$	ns
			$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$	–	–	$1.5tcyc + 200$	ns
tor	SSI slave out open time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	–	–	$1.5tcyc + 100$	ns
			$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$	–	–	$1.5tcyc + 200$	ns

Notes:

1. $V_{CC} = 1.8$ to 5.5 V , $V_{SS} = 0\text{ V}$ and $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. $1tcyc = 1/f_1(\text{s})$

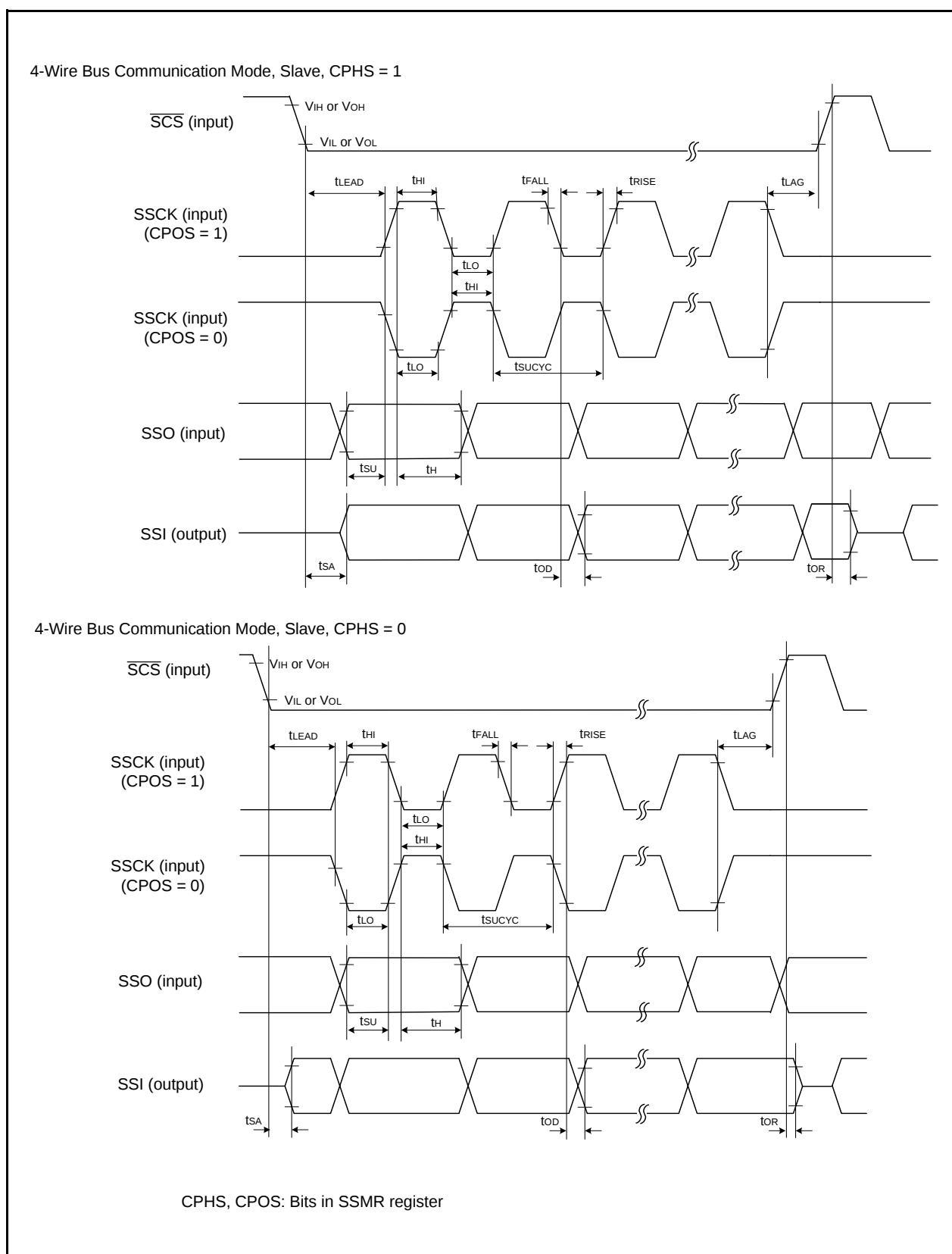


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

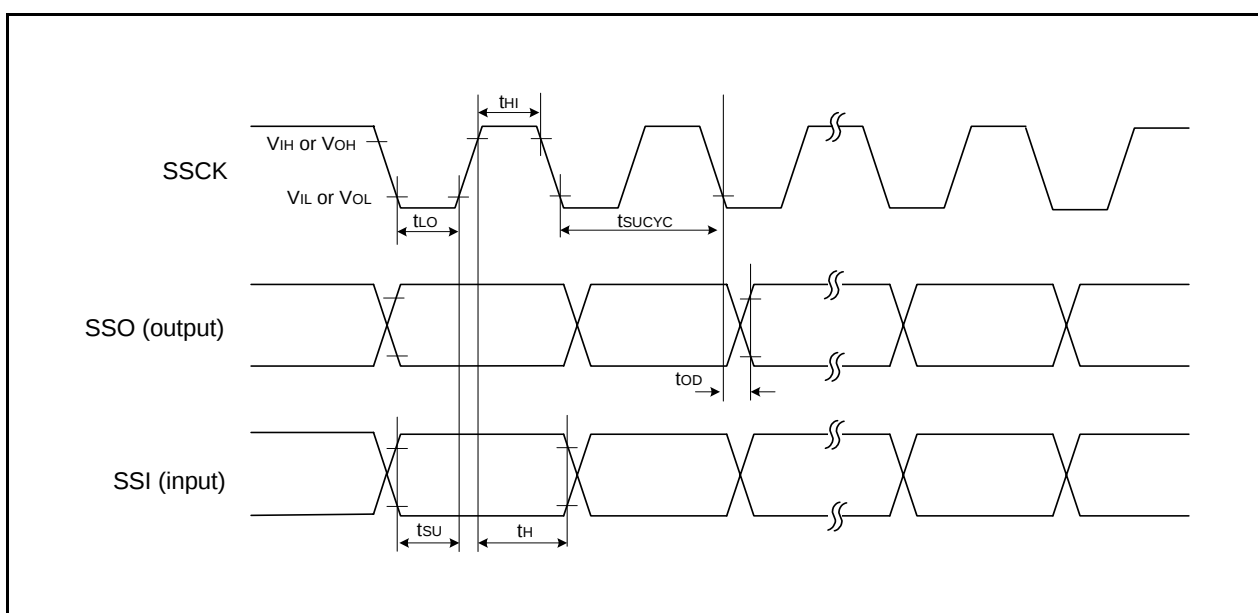


Figure 5.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

Table 5.16 Timing Requirements of I²C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{cy} + 600 (2)	–	–	ns
t _{SCLH}	SCL input “H” width		3t _{cy} + 300 (2)	–	–	ns
t _{SCLL}	SCL input “L” width		5t _{cy} + 500 (2)	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1t _{cy} (2)	ns
t _{BUF}	SDA input bus-free time		5t _{cy} (2)	–	–	ns
t _{STAH}	Start condition input hold time		3t _{cy} (2)	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3t _{cy} (2)	–	–	ns
t _{STOP}	Stop condition input setup time		3t _{cy} (2)	–	–	ns
t _{SDAS}	Data input setup time		1t _{cy} + 40 (2)	–	–	ns
t _{SDAH}	Data input hold time		10	–	–	ns

Notes:

1. V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. 1t_{cy} = 1/f₁(s)

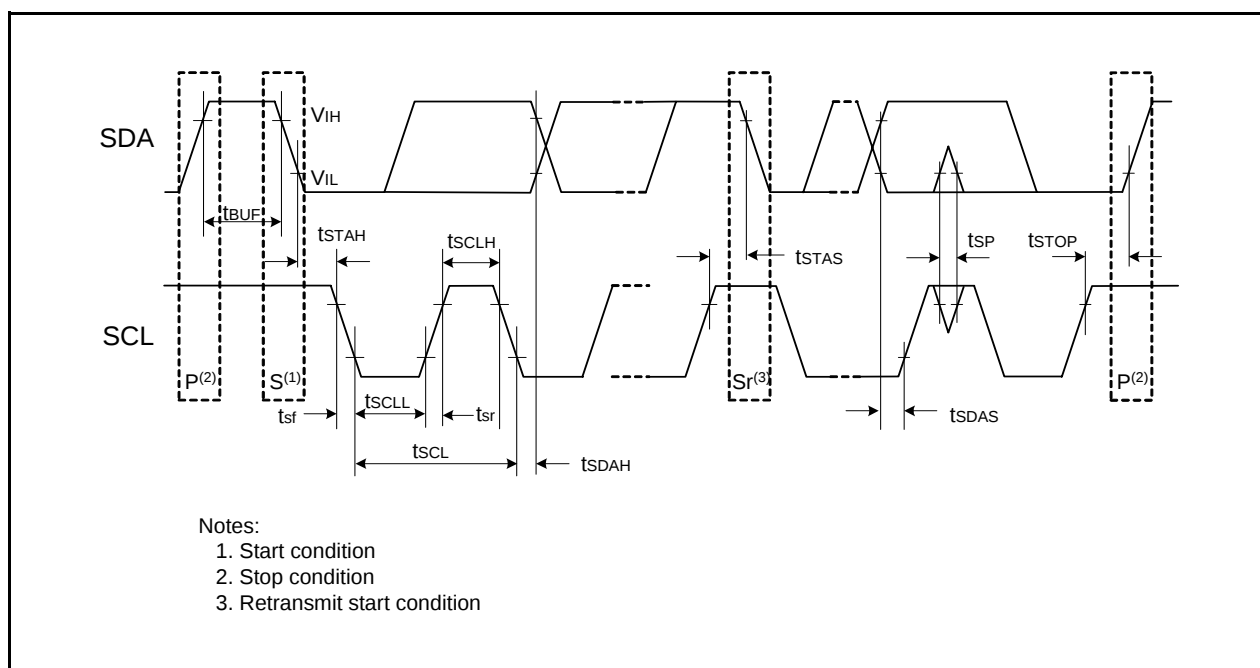
**Figure 5.7 I/O Timing of I²C bus Interface**

Table 5.17 Electrical Characteristics (1) [$4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High V _{CC} = 5 V	I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity Low V _{CC} = 5 V	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	V _{CC} = 5 V	I _{OH} = -200 μA	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High V _{CC} = 5 V	I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity Low V _{CC} = 5 V	I _{OL} = 5 mA	—	—	2.0	V
		XOUT	V _{CC} = 5 V	I _{OL} = 200 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	—	V
		RESET			0.1	1.2	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5.0 V		—	—	5.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5.0 V		—	—	-5.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5.0 V		25	50	100	kΩ
R _{FXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R _{FXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

1. $4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ and T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.18 Electrical Characteristics (2) [$3.3\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

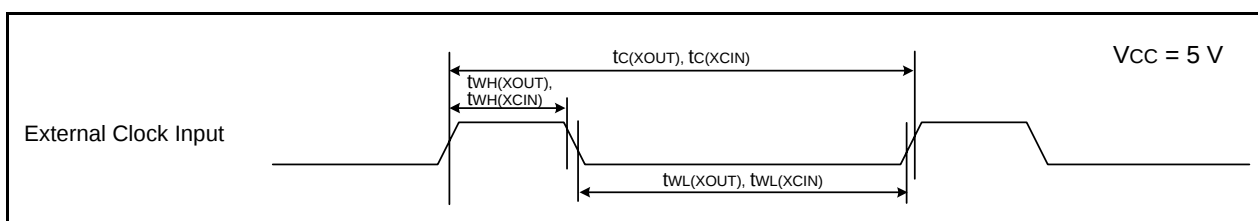
Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	6.5	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.3	12.5	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	3.6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.2	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 4 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-16, MSTIIC = MSTTRD = MSTTRC = 1	–	1	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	–	90	400	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division, FMR27 = 1, VCA20 = 0	–	85	400	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division, Program operation on RAM Flash memory off, FMSTP = 1, VCA20 = 0	–	47	–	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	15	100	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	4	90	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (peripheral clock off) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	3.5	–	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1, Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	2.0	5.0	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1, Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	5.0 (1) 15 (2)	–	μA

Notes:

- Value when the program ROM capacity of the product is 16 Kbytes to 32 Kbytes.
- Value when the program ROM capacity of the product is 48 Kbytes to 128 Kbytes.

Timing Requirements(Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^{\circ}\text{C}$)**Table 5.19 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	24	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	24	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	μs
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	μs
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	μs

**Figure 5.8 External Clock Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.20 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	100	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	40	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	40	—	ns

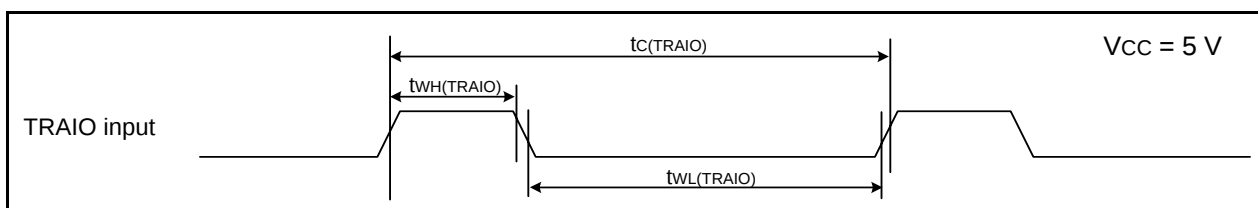
**Figure 5.9 TRAIO Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.29 Electrical Characteristics (5) [$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High	I _{OH} = -2 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity Low	I _{OH} = -1 mA	V _{CC} - 0.5	—	V _{CC}	V
		XOUT		I _{OH} = -200 μA	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High	I _{OL} = 2 mA	—	—	0.5	V
			Drive capacity Low	I _{OL} = 1 mA	—	—	0.5	V
		XOUT		I _{OL} = 200 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.2	—	V
		RESET			0.05	0.20	—	V
I _{IH}	Input "H" current		V _I = 2.2 V, V _{CC} = 2.2 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 2.2 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 2.2 V		70	140	300	kΩ
R _{FXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R _{FXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

1. $1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$ and $T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), $f(\text{XIN}) = 5\text{ MHz}$, unless otherwise specified.

REVISION HISTORY	R8C/35C Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.10	Sep. 01, 2009	–	First Edition issued
1.00	Aug. 24, 2010	All 4 27 to 53	“Preliminary” and “Under development” deleted Table1.3 revised 5. Electrical Characteristics added

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